

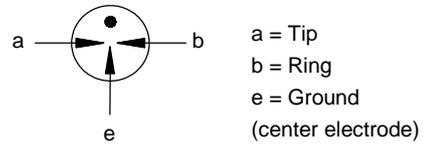
**Description**

GDT is placed in front of, and in parallel with, sensitive telecom equipment such as power lines, communication lines, signal lines and data transmission lines to help protect them from damage caused by transient surge voltages that may result from lightning strikes and equipment switching operations. These devices do not influence the signal in normal operation. However, in the event of an overvoltage surge, such as a lightning strike, the GDT switches to a low impedance state and diverts the energy away from the sensitive equipment.

Our GDT offer a high level of surge protection, a broad voltage range, low capacitance, and many form factors including new surface mount devices, which makes them suitable for applications such as Main Distribution Frame (MDF) modules, high data-rate telecom applications (e.g. ADSL, VDSL), and surge protection on power lines. Their low capacitance also results in less signal distortion. When used in a coordinated circuit protection solution with PolySwitch devices, they can help equipment manufacturers meet stringent safety regulatory standards.



**Electrical symbol**



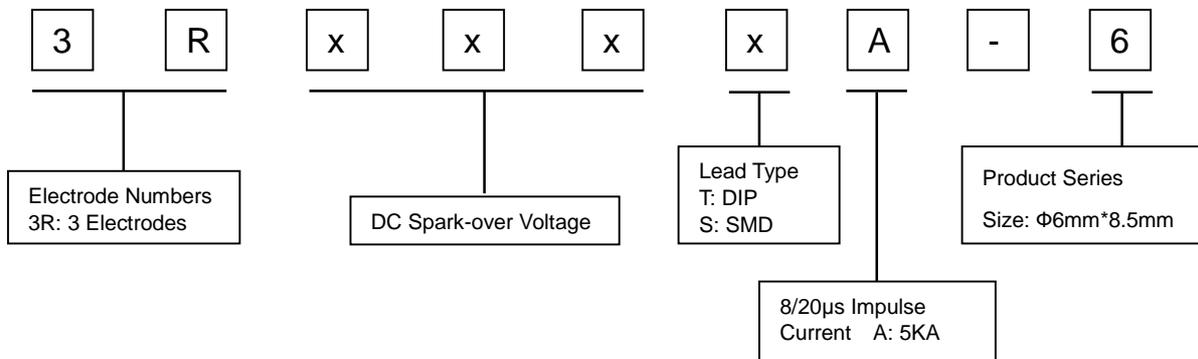
**Features**

- I Excellent response to fast rising transients
- I Stable breakdown voltage
- I GHz working frequency
- I 8/20 $\mu$ s Impulse current capability: 10KA
- I Non-Radioactive
- I Ultra Low capacitance (<1.5pF)
- I High insulation resistance
- I Lead-free compliant
- I RoHS and REACH compliant
- I UL 497B Recognized: E465335
- I Size:  $\Phi$ 6mm\*8.5mm
- I Storage and operational temperature: -40~+90°C

**Applications**

- I Communication equipment
- I CATV equipment
- I Data lines
- I Power supplies
- I Telecom SLIC protection
- I Broadband equipment
- I ADSL equipment, including ADSL2+
- I XDSL equipment
- I Satellite and CATV equipment
- I Test equipment
- I Consumer electronics

**Part Number Code**



Electrical Characteristics

Part Number			DC Spark-over Voltage <sup>1) 2)</sup> @100V/S	Impulse Spark-over Voltage <sup>3)</sup>		Insulation Resistance <sup>4)</sup>	Capacitance @1MHz	Life Ratings				
				100V/μS	1KV/μS			Impulse Discharge Current @8/20μs <sup>5)</sup>		AC Discharge Current @50Hz 1S <sup>5)</sup>	Impulse Life @10/1000μS 100A <sup>5)</sup>	
				Max	Max			Min	Max			Nominal ±5 times
DIP	SMD	DIP-F	V	V	V	GΩ	pF	KA	KA	A	Times	
3R070TA-6	3R070SA-6	3R070TA-6F	70±20%	500	600	1	1.5	5	10	5	300	
3R075TA-6	3R075SA-6	3R075TA-6F	75±20%	500	600	1	1.5	5	10	5	300	
3R090TA-6	3R090SA-6	3R090TA-6F	90±20%	750	850	1	1.5	5	10	5	300	
3R150TA-6	3R150SA-6	3R150TA-6F	150±20%	750	850	1	1.5	5	10	5	300	
3R230TA-6	3R230SA-6	3R230TA-6F	230±20%	600	700	1	1.5	5	10	5	300	
3R250TA-6	3R250SA-6	3R250TA-6F	250±20%	600	700	1	1.5	5	10	5	300	
3R300TA-6	3R300SA-6	3R300TA-6F	300±20%	700	900	1	1.5	5	10	5	300	
3R350TA-6	3R350SA-6	3R350TA-6F	350±20%	700	900	1	1.5	5	10	5	300	
3R400TA-6	3R400SA-6	3R400TA-6F	400±20%	800	1000	1	1.5	5	10	5	300	
3R470TA-6	3R470SA-6	3R470TA-6F	470±20%	900	1100	1	1.5	5	10	5	300	
3R600TA-6	3R600SA-6	3R600TA-6F	600±20%	1100	1300	1	1.5	5	10	5	300	
3R800TA-6	3R800SA-6	3R800TA-6F	800±20%	1300	1500	1	1.5	5	10	5	300	
Glow Voltage at 10mA.....						~60V						
Arc Voltage at 1A.....						~10V						
Glow to Arc transition Current.....						~1A						
Operation and storage temperature.....						-40~+90°C						
Climatic category (IEC60068-1).....						40/90/21						
Marking, Blue.....						<b>RUILON</b> <b>xxx A X</b> xxx -Nominal voltage A -Nominal Impulse Discharge Current X -Year of production						
Weight.....						~1.25g						
Surface treatment.....						DIP -Nickel Plated SMD -Matte-tin plated						

1) At delivery AQL 0.65 level II, DIN ISO 2859

2) In ionized mode

3) Tip or ring electrode to center electrode

4) Insulation Resistance Measuring Voltage:

70V, 75V at DC 25V

90V~150V at DC 50V

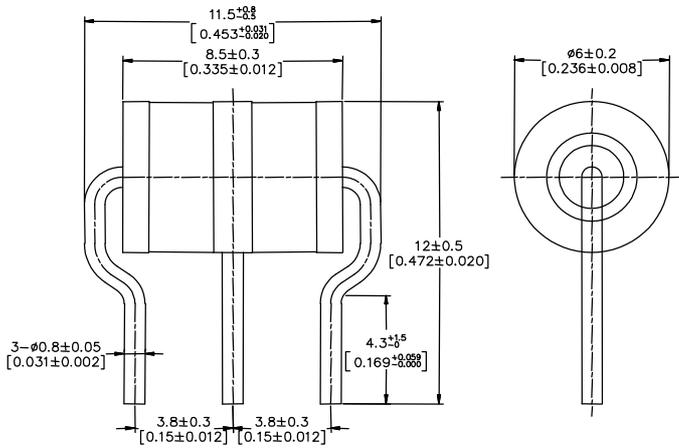
Other at DC 100V

5) Total current through center electrode, half value through tip respectively ring electrode.

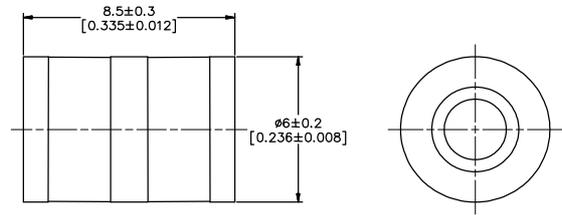
Terms in accordance with ITU-T Rec. K.12, IEC 61643-311, GB/T 9043.

Dimensions (Unit: mm/inch)

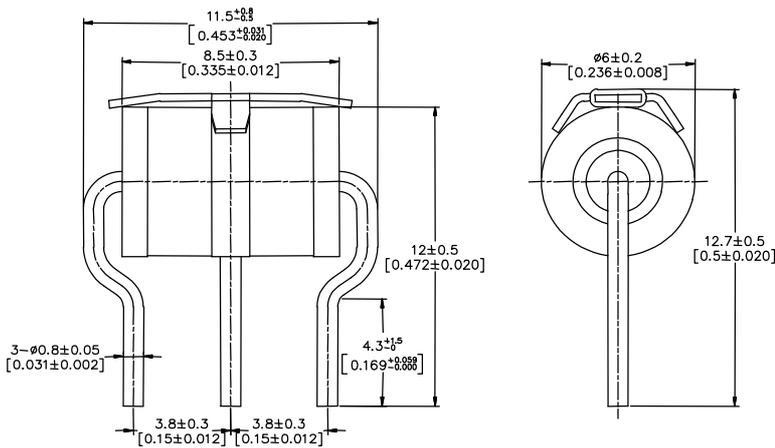
DIP Series (3RxxxTA-6)



SMD Series (3RxxxSA-6)

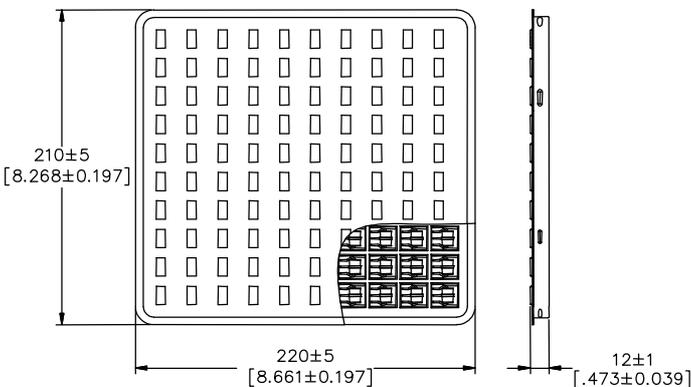


DIP Series (3RxxxTA-6F)

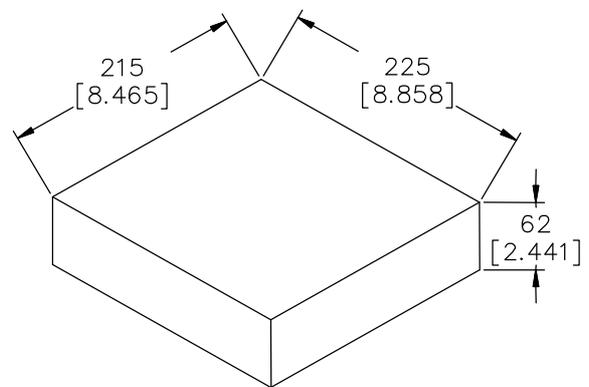


Packaging Information (Unit: mm/inch)

“DIP Series” and “DIP-F Series” Packaging (Bulk)

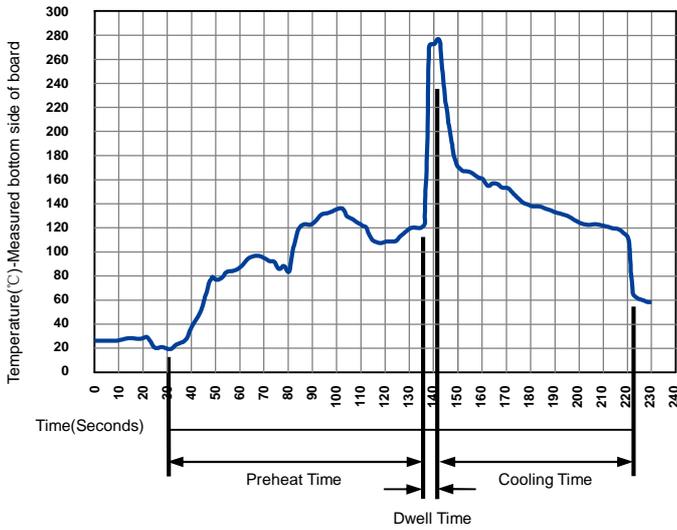


100PCS/ Plastic Tray



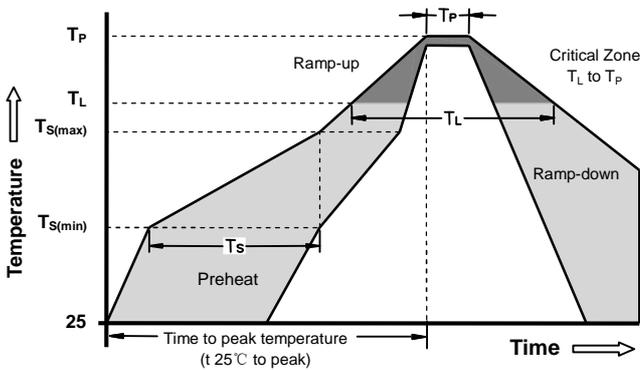
500PCS, 5 Plastic Trays / Inner Box

**Soldering Parameters - Wave soldering (Thru-Hole Devices)**



Wave Soldering Condition		Pb-Free assembly
Preheat	Temperature Min	100°C
	Temperature Max	150°C
	Time (Min to Max)	60-180 Seconds
Solder Pot Temperature		280°C Max
Solder Dwell Time		2-5 Seconds

**Soldering Parameters - Reflow Soldering (Surface Mount Devices)**



Reflow Condition		Pb - Free assembly
Preheat	-Temperature Min ( $T_{S(min)}$ )	150°C
	-Temperature Max ( $T_{S(max)}$ )	200°C
	- Time (min to max) ( $t_s$ )	60 -180 Seconds
Average ramp up rate ( Liquids Temp $T_L$ to peak)		3°C/second max
$T_{S(max)}$ to $T_L$ - Ramp-up Rate		5°C/second max
Reflow	- Temperature ( $T_L$ ) (Liquids)	217°C
	- Time (min to max) ( $t_s$ )	60 -150 Seconds
Peak Temperature ( $T_P$ )		260 +0/-5°C
Time within 5°C of actual peak Temperature ( $t_p$ )		10 - 30 Seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature ( $T_P$ )		8 minutes Max
Do not exceed		260°C